## RDT SERIES ROTARY DIP SwITCH



Applications / Markets


## Specifications

## Electrical Rating:

Switching: 42VDC, 150mA
Non-Switching: 42VDC, 200 mA
Life Expectancy: 10,000 steps
Contact Resistance: $80 \mathrm{~m} \Omega$ Max.
Insulation Resistance: $100 \mathrm{M} \Omega \mathrm{Min}$. at 250VDC
Dielectric Strength: 250VAC
Operating Temperature:
$-40^{\circ} \mathrm{C}$ to $85^{\circ} \mathrm{C}$ (Thru Hole)
$-60^{\circ} \mathrm{C}$ to $125^{\circ} \mathrm{C}$ (SMT)
Actuation Force: $700 \mathrm{gf}-\mathrm{cm}$ Max
Travel: dependent upon individual switch positions

## Features \& Benefits

- Offers IP67 ratings for A, B, and D actuators
- Available in 4, 6, 8, 10 and 16 positions
- Right angle or vertical options
- SMT or thru hole options
- Gold contacts
- Tape \& Reel packaging for S1 and S2 termination

Part Number Configurator


E-SWITCH $\qquad$

## RDT Series Rotary DIP Switch

## Body Dimensions

Vertical


## General Codes

Right Angle



4 POSITION

REAL CODE

|  | $C$ | 1 | 2 | 4 | 8 |
| :--- | :--- | :--- | :--- | :--- | :--- |
| 0 | $\bullet$ |  |  |  |  |
| 1 | $\bullet$ | $\bullet$ |  |  |  |
| 2 | $\bullet$ |  | $\bullet$ |  |  |
| 3 | $\bullet$ | $\bullet$ | $\bullet$ |  |  |
| 4 | $\bullet$ |  |  |  |  |
| 5 |  | $\bullet$ |  | $\bullet$ |  |
| 6 | $\bullet$ |  |  | $\bullet$ |  |
| 7 | $\bullet$ |  |  |  |  |

8 POSITION



6 POSITION

COMPLEMENT CODE


10 POSITION


16 POSITION


10 POSITION


16 POSITION

## Actuator Options


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## RDT Series Rotary DIP Switch

## Actuator Options

(Cont.)

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## RDT Series Rotary DIP Switch

## Terminaiton Options

P1-Vertical


P2-Vertical


Vertical P2 PCB Layout


## RDT SERIEs Rotary DIP Switch

Termination Options
(Cont.)

S2-Vertical


R2-Right Angle

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## RDT Series Rotary DIP Switch

## Body Dimensions

Tape and Reel

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## Recommended <br> Solder Process

Most contamination problems can be prevented by exercising care during the cleaning and soldering process. Care should be taken not to immerse or spray unsealed switches during flux removal. Contact E-Switch for specific soldering recommendations and specifications not shown. Generalized soldering procedures are outlined below.

## "TYPICAL" SMT REFLOW (Pb and Pb-Free)

| Profile Feature | Sn-Pb Eutectic Assembly | Pb-Free Assembly |
| :---: | :---: | :---: |
| Average Ramp-Up Rate ( $\mathrm{Ts}_{\text {max }}$ to Tp ) | $3^{\circ} \mathrm{C} /$ second max. | $3^{\circ} \mathrm{C} /$ second max. |
| Preheat <br> -Temperature $\mathrm{Min}\left(\mathrm{T} s_{\text {min }}\right)$ <br> -Temperature $\mathrm{Max}^{\left(T s_{\text {max }}\right)}$ <br> -Time $\left(\mathrm{ts}_{\text {min }}\right.$ to $\left.\mathrm{ts} \mathrm{s}_{\max }\right)$ | $\begin{gathered} 100{ }^{\circ} \mathrm{C} \\ 150{ }^{\circ} \mathrm{C} \\ 60-120 \text { seconds } \end{gathered}$ | $\begin{gathered} 150^{\circ} \mathrm{C} \\ 200^{\circ} \mathrm{C} \\ 60-180 \text { seconds } \end{gathered}$ |
| Time Maintained above: <br> -Temperature ( $\mathrm{T}_{\mathrm{L}}$ ) <br> -Time ( $\mathrm{t}_{\mathrm{L}}$ ) | $\begin{gathered} 183{ }^{\circ} \mathrm{C} \\ 60-150 \text { seconds } \end{gathered}$ | $\begin{gathered} 217{ }^{\circ} \mathrm{C} \\ 60-150 \text { seconds } \end{gathered}$ |
| Time within $5^{\circ} \mathrm{C}$ of actual Peak Temperature (tp) | 10-30 seconds | 20-40 seconds |
| Ramp-Down Rate | $6^{\circ} \mathrm{C} /$ second max. | $6^{\circ} \mathrm{C} /$ second max. |
| Time $25^{\circ} \mathrm{C}$ to Peak Temperature | 6 minutes max. | 8 minutes max. |

Note 1: All temperatures refer to topside of the package, measured on the package surface.


